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Full Material Declaration for attached parts list

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Diotec Semiconductor AG

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Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 1 January 2009 [Approved on 19 September 2016, 15:11 GMT]

Materials and substances

Use/Location	Material group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.50000%	Silicon dioxide	60676-86-0	1.00000%
			Gold	7440-57-5	4.50000%
			Silicon	7440-21-3	94.50000%
Die attach	Lead and Lead alloys	0.20000%	Silver	7440-22-4	2.50000%
			Tin	7440-31-5	5.00000%
			Lead	7439-92-1	92.50000%
Encapsulation	EP (Epoxy resin)	33.00000%	1,3-Isobenzofurandione, hexahydro-5-methyl-	19438-60-9	0.10000%
			Low molecular weight solid DGEBPA- based epoxy resins	25068-38-6	1.25000%
			Benzyl-N,N-dimethylamine	103-83-3	3.10000%
			1,3- Isobenzofurandione, 3a,4,7,7a- tetrahydro- 4- methyl-	5333-84-6	6.00000%
			cis-1,2,3,6- Tetrahydrophthalic anhydride	85-43-8	9.25000%
			1,3-Isobenzofurandione, tetrahydro-5-methyl-	34090-76-1	10.65000%
			7- Oxabicyclo(4.1.0)heptane- 3- carboxylic acid, 7- oxabicyclo(4.1.0)hept- 3- ylmethyl ester	2386-87-0	14.65000%
			Silica	14808-60-7	55.00000%
Housing	UP (Unsaturated polyester)	26.00000%	ANTIMONY TRIOXIDE	1309-64-4	17.00000%
			polyethylene-ethyl acrylate	9010-86-0	28.00000%

			Glass fibers	65997-17-3	55.00000%
Leadfinish	Tin plating	0.10000%	Tin	7440-31-5	100.00000%
Leadframe	Copper (e.g. copper amounts in cable harnesses)	40.20000%	Copper	7440-50-8	100.00000%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
KBPC8xx	Bridge Rectifier Square	5.5	g

Based on the information currently available, these substances do not pose any risk if the articles are used as intended (including disposal). Additional information is not necessary to allow safe use of the article.